

Dear Customer,

Please find attached our INFINEON Technologies PCN:

GEM Shanghai (China) will be the alternate assembly site for the IPak products

Important information for your attention:

- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On January 13, 2015, Infineon Technologies acquired International Rectifier. The organization and business of former International Rectifier have been integrated into Infineon. That means that customer facing IT tools and processes like PCN, Information Note and Product Discontinuation are being merged consolidated. For further details please visit our website:
<http://www.infineon.com/powerfulcombination>

Infineon Technologies AG
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Arunjai Mittal
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Date: Tuesday, April 19, 2016
PCR Reference: 770
PCN Reference: 770-PCN90-Public

To Our Valued Customer:

As always we appreciate your use of Infineon Technologies semiconductor products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our change plans to enhance capacity, quality and reliability. This notice is to inform you of the following change:

We would like to express our sincere appreciation for your cooperation regarding the following changes, and Infineon Technologies will work closely with you to support your requirements during this transition.

Type of Change Notification:

Additional assembly site qualification

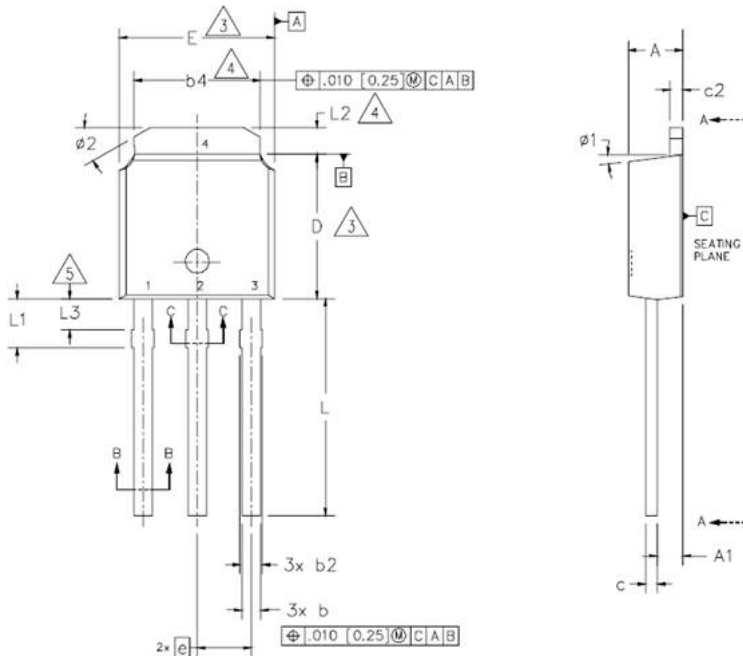
Description of Change:

GEM Shanghai (China) will be the alternate assembly site for the IPak products

As the result of this change, the Bill of Materials and POD at the new assembly site will be as follows:

Material	Before	After
Die attach	Material # 44-0153	Material # 44-0312
Wire interconnect	Material # 44-0199	Material # 44-0199
Mold compound	Material # 44-0173	Material # 44-0758
Leadframe	Material # 44-0159	Material # 44-1522

POD Detail



IR, JEDEC, GEM IPAK(TO-251) PACKAGE OUTLINE COMPARISON

SYMBOL	SYMBOL DESCRIPTION	IR		JEDEC		GEM		REMARKS
		INCH		INCH		INCH		
		MIN	MAX	MIN	MAX	MIN	MAX	
A	Package thickness	086	094	086	094	087	094	GEM is JEDEC & IR Compliant
A1	Btm of leads to btm of pkg	035	045	350	050	035	045	GEM is JEDEC & IR Compliant
b	Leadwidth(with plating)	025	035	025	035	026	035	GEM is JEDEC & IR Compliant
b2	Standoff width(with plating)	030	045	030	045	030	045	GEM is JEDEC & IR Compliant
b4	Thermal pad width width	195	215	195	215	197	215	GEM is JEDEC & IR Compliant
c	Lead thickness(with plating)	018	024	018	024	018	024	GEM is JEDEC & IR Compliant
c1	Lead thickness(no plating)	016	022	016	022	016	022	GEM is JEDEC & IR Compliant
c2	Heatsink thickness	018	035	018	035	018	035	GEM is JEDEC & IR Compliant
D	Package height	235	245	235	245	236	244	GEM is JEDEC & IR Compliant
D1	Thermal pad length	205	-	205	-	205	-	GEM is JEDEC & IR Compliant
E	Package width	250	265	250	265	252	265	GEM is JEDEC & IR Compliant
E1	Thermal pad width	170	-	170	-	170	-	GEM is JEDEC & IR Compliant
e	Lead pitch	090 BSC		090 BSC		090 BSC		GEM is JEDEC & IR Compliant
L	Total lead length	350	380	350	380	354	370	GEM is JEDEC & IR Compliant
L1	Pkg to btm of lead stand off	045	090	075	090	075	090	GEM is JEDEC & IR Compliant
L2	Top of heat sink to mold pkg	035	050	035	050	039	050	GEM is JEDEC & IR Compliant
L3	Pkg to top of lead stand off	045	060	045	060	037	047	Minimum dim does not meet JEDEC & IR spec.

Reason for the Change:

Additional assembly capacity

Effect Date:

Monday, July 18, 2016

Impact of Change:

The package outline dimensions (POD) will be changed at the new assembly site (See description)

Method of Identifying Changed Product:

By date code and lot code product marking

Products Affected:

IFAM Part	Description
IRFU1010ZPBF	MOSFET, 55V, 91A, 7.5 mOhm, 63 nC Qg, I-Pak
IRFU1018EPBF	MOSFET, 60V, 79A, 8.4 mOhm, 46 nC Qg, I-Pak
IRFU1205PBF	MOSFET, 55V, 37A, 27 mOhm, 43.3 nC Qg, I-Pak
IRFU12N25DPBF	
IRFU13N20DPBF	MOSFET, 200V, 14A, 235 mOhm, 25 nC Qg, I-Pak
IRFU15N20DPBF	
IRFU18N15DPBF	
IRFU2405PBF	MOSFET, 55V, 56A, 16 mOhm, 70 nC Qg, I-Pak
IRFU2407PBF	
IRFU24N15DPBF	
IRFU3410PBF	MOSFET, 100V, 31A, 39 mOhm, 37 nC Qg, I-Pak
IRFU3411PBF	
IRFU3505PBF	
IRFU3607PBF	MOSFET, 75V, 80A, 9.0 mOhm, 56 nC Qg, I-Pak
IRFU3710ZPBF	MOSFET, 100V, 56A, 18 mOhm, 69 nC Qg, I-Pak
IRFU4104PBF	MOSFET, 40V, 119A, 5.5 mOhm, 59 nC Qg, I-Pak
IRFU4510PBF	MOSFET, 100V, 63A, 13.9 mOhm, 54 nC Qg, I-Pak
IRFU4615PBF	MOSFET, 150V, 33A, 42mOhm, 26nC Qg, I-Pak
IRFU4620PBF	MOSFET, 200V, 24A, 78mOhm, 25nC Qg, I-Pak
IRFU7440PBF	
IRLU2905PBF	
IRLU2908PBF	
IRLU3103PBF	MOSFET, 30V, 46A, 19 mOhm, 33.3 nC Qg, Logic Level, I-Pak
IRLU3110ZPBF	MOSFET, 100V, 63A, 14 mOhm, 34 nC Qg, Logic Level, I-Pak
IRLU3114ZPBF	MOSFET, 40V, 130A, 4.9 mOhm, 40 nC Qg, Logic Level, I-Pak
IRLU3636PBF	MOSFET, 60V, 99A, 6.8 mOhm, 33 nC Qg, Logic Level, I-Pak
IRLU3705ZPBF	MOSFET, 55V, 89A, 8 mOhm, 44 nC Qg, Logic Level, I-Pak
IRLU3915PBF	MOSFET, 55V, 61A, 14 mOhm, 61 nC Qg, Logic Level, I-Pak

Process / Product Change Notification



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IFAM Part	Description
IRLU7833PBF	
IRLU7843PBF	MOSFET, 30V, 161A, 3.3 mOhm, 34 nC Qg, Logic Level, I-Pak
IRLU8743PBF	MOSFET, 30V, 160A, 3.1 mOhm, 39 nC Qg, Logic Level, I-Pak

Qualification:

Parts passed all the reliability testing requirements. Reliability qualification report is available upon request.

Supporting Data Availability:

Contact Infineon Technologies for supporting data on this change.

Contact Information:

CONTACT TYPE	NAME	PHONE	EMAIL
PCN Coordinator	Abigail Miciano		Abigail.Miciano@infineon.com
Technical Contact	Cesar Gonzales		Cesar.Gonzales@infineon.com